

Features

Fast response times High photo sensitivity Small junction capacitance Pb free The product itself will remain within RoHS compliant version Compliancewith EU REACH



Application

High speed photo detector Camera Optoelectronic switch VCRs , Video camera

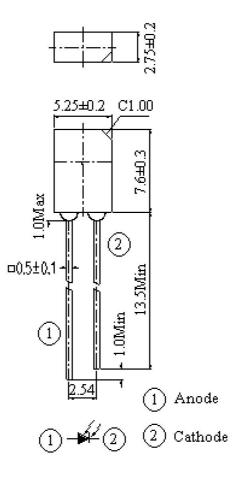
Description

PD600B is a high speed and sensitive PIN photodiode in a cylindrical side view plastic package. The epoxy package itself is an IR filter , spectrally matched to IR emitter.





PACKAGE DIMENSIONS



NOTES:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm(.010") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.

PD600B



ABSOLUTE MAXIMUM RATINGS AT TA =25°C

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	32	mA
Power Dissipation	Pd	150	mW
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Soldering Temperature(*1)	T _{sol}	260	C

Notes: *1 Soldering time≦5 seconds

PD600B



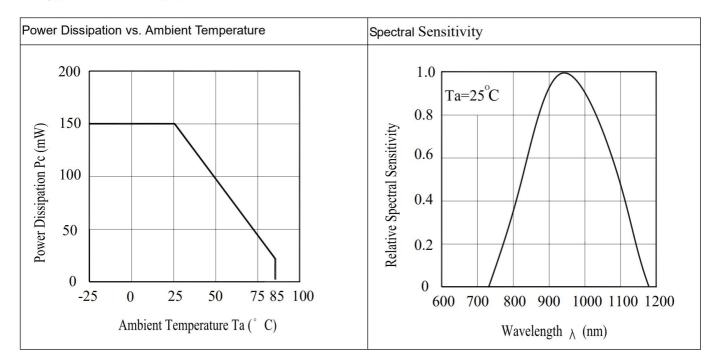
ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C

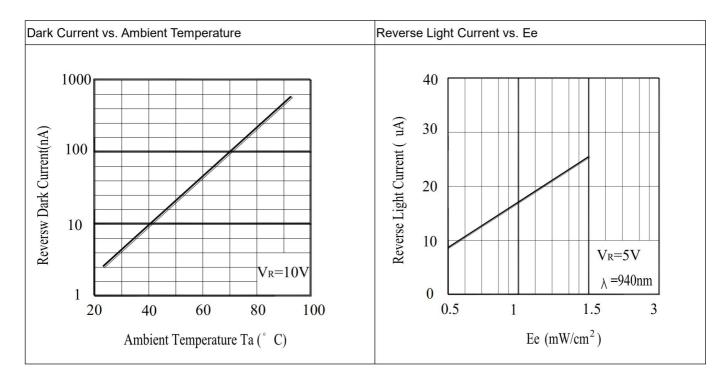
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Rang of Spectral Bandwidth	λ0.5	840		1100	nm	
Wavelength of Peak Sensitivity	λр		940		nm	
Open-Circuit Voltage	VOC		0.35		V	Ee=5m W/cm2 λp=940nm
Short- Circuit Current	ISC		18		uA	Ee=1m W/cm2 λp=940nm
Reverse Light Current	IL	10.2	18		uA	Ee=1m W/cm2 λp=940nm VR=5V
Dark Current	ld		5	30	nA	Ee=0m W/cm2 VR=10V
Reverse Breakdown	BVR	32	170		v	Ee=0m W/cm2 IR=100µA
Total Capacitance	Ct		25		pF	Ee=0m W/cm2 VR=3V f=1MHZ
Rise/Fall Time	tr/tf		50/50		nS	VR=10V RL=1KΩ

PD600B



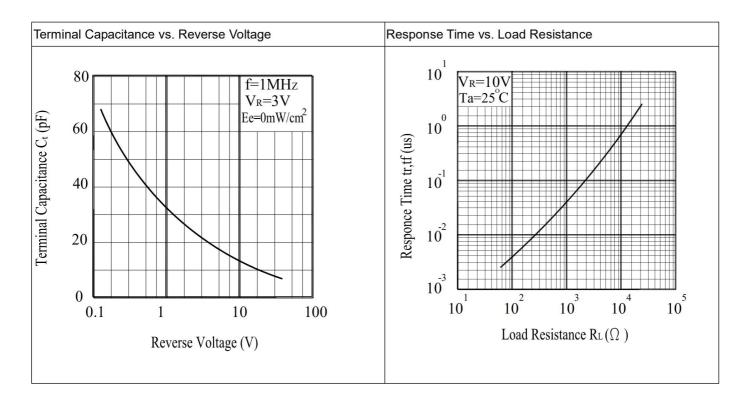
Typical Electro-Optical Characteristics Curves





PD600B





PD600B



Packing Quantity Specification

- 1. 1000Pcs/1Bag, 10 Bag/1Box
- 2. 4Boxes/1Carton

Label Form Specification



- · PRODUCT: Part Number
- · CODE NO.: Product Serial Number
- · QTY: Packing Quantity
- · LOT No: Lot Number
- · REMARKS:Remarks

Notes Lead Forming

1. During lead frame bending, the lead frame should be bent at a distance more than 3mm from bottom of the epoxy.

Note: Must fix lead frame and do not touch epoxy before bending to avoid Photodiode broken.

2.Lead forming should be done before soldering.

3. Avoid stressing the Photodiode package during leads forming. The stress to the base may damage the Photodiode's characteristics or it may break the Photodiode.

4.Cut the Photodiode lead frame at room temperature. Cutting the lead frame at high temperatures may cause failure of the Photodiode.

5. When mounting the Photodiode onto a PCB, the PCB holes must be aligned exactly with the lead position of the Photodiode. If the Photodiode are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the Photodiode.



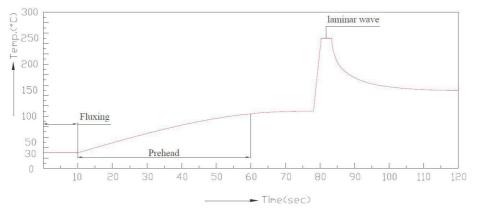
Soldering

1. Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.

2. Recommended soldering conditions:

Hand Soldering		DIP Soldering		
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)	
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max	
	3mm Min.(From solder		3mm Min. (From solder joint	
Distance	joint to epoxy bulb)	Distance	to epoxy bulb)	

3. Recommended soldering profile



4. Avoiding applying any stress to the lead frame while the Photodiode are at high temperature particularly when soldering.

5.Dip and hand soldering should not be done more than one time

6.After soldering the Photodiode, the epoxy bulb should be protected from mechanical shock or vibration until the Photodiode return to room temperature.

7.A rapid-rate process is not recommended for cooling the Photodiode down from the peak temperature.

8.Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the Photodiode.

9. Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.



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